

Notice of References Cited	Application/Control No. 09/674,090	Applicant(s)/Patent Under Reexamination EICHEN ET AL.	
	Examiner Young J. Kim	Art Unit 1637	Page 1 of 1

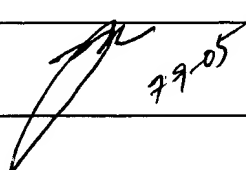
U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Braun et al., "DNA-templated assembly and electrode attachment of a conducting silver wire," Nature, February 19, 1998, vol. 391, pages 775-778.
	V	
	W	
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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